

## 150V N-Channel Enhancement Mode Power MOSFET

### Description

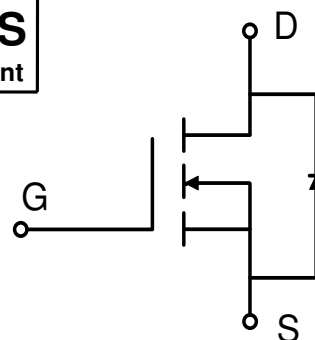
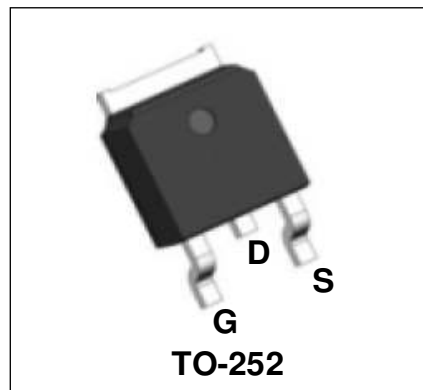
WMO20N15T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

### Features

- $V_{DS} = 150V$ ,  $I_D = 20A$   
 $R_{DS(on)} < 78m\Omega$  @  $V_{GS} = 10V$   
 $R_{DS(on)} < 90m\Omega$  @  $V_{GS} = 4.5V$
- High Speed Power Switching
- Low Gate Charge
- 100% EAS Guaranteed
- Lead Free

### Applications

- Synchronous Rectification in SMPS
- Hard Switching and High Speed Circuit
- Power Tools
- UPS
- Motor Control



### Absolute Maximum Ratings

Parameter		Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	150	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1</sup>	$T_C = 25^\circ C$	$I_D$	20	A
	$T_C = 100^\circ C$		14	
Pulsed Drain Current <sup>2</sup>		$I_{DM}$	41	A
Single Pulse Avalanche Energy <sup>3</sup>		EAS	25	mJ
Avalanche Current		$I_{AS}$	13	A
Total Power Dissipation <sup>4</sup>	$T_C = 25^\circ C$	$P_D$	61	W
Operating Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 to 175	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	$R_{\theta JA}$	59	$^\circ C/W$
Thermal Resistance from Junction-to-Case <sup>1</sup>	$R_{\theta JC}$	2.45	$^\circ C/W$

**Electrical Characteristics**  $T_c = 25^\circ\text{C}$ , unless otherwise noted

Parameter		Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics							
Drain-Source Breakdown Voltage		V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	150	-	-	V
Gate-body Leakage current		I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	T <sub>J</sub> = 25℃	I <sub>DSS</sub>	V <sub>DS</sub> = 150V, V <sub>GS</sub> = 0V	-	-	1	μA
	T <sub>J</sub> = 100℃			-	-	100	
Gate-Threshold Voltage		V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1	2	3	V
Drain-Source On-Resistance <sup>2</sup>		R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A	-	63	78	mΩ
			V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 8A		72	90	
Forward Transconductance <sup>2</sup>		g <sub>fs</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 10A	-	24	-	S
Dynamic Characteristics							
Input Capacitance		C <sub>iss</sub>	V <sub>DS</sub> = 75V, V <sub>GS</sub> = 0V, f = 1MHz	-	630	-	pF
Output Capacitance		C <sub>oss</sub>		-	50	-	
Reverse Transfer Capacitance		C <sub>rss</sub>		-	13.5	-	
Switching Characteristics							
Gate Resistance		R <sub>g</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> =0V f = 1MHz	-	4	-	Ω
Total Gate Charge		Q <sub>g</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 75V, I <sub>D</sub> = 10A	-	10.5	-	nC
Gate-Source Charge		Q <sub>gs</sub>		-	1.2	-	
Gate-Drain Charge		Q <sub>gd</sub>		-	3.8	-	
Turn-On Delay Time		t <sub>d(on)</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 75V, R <sub>G</sub> = 10Ω, I <sub>D</sub> = 10A	-	9.8	-	nS
Rise Time		t <sub>r</sub>		-	6	-	
Turn-Off Delay Time		t <sub>d(off)</sub>		-	15	-	
Fall Time		t <sub>f</sub>		-	4.1	-	
Drain-Source Body Diode Characteristics							
Diode Forward Voltage <sup>2</sup>		V <sub>SD</sub>	I <sub>S</sub> = 10A, V <sub>GS</sub> = 0V	-	-	1.2	V
Continuous Source Current <sup>1,5</sup>		I <sub>S</sub>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	-	-	20	A
Body Diode Reverse Recovery Time		t <sub>rr</sub>	V <sub>R</sub> = 75V, I <sub>F</sub> = 10A, dl/dt= 100A/μs	-	56	-	nS
Body Diode Reverse Recovery Charge		Q <sub>rr</sub>		-	125	-	nC

## Notes:

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.3mH, I_{AS}=13A$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

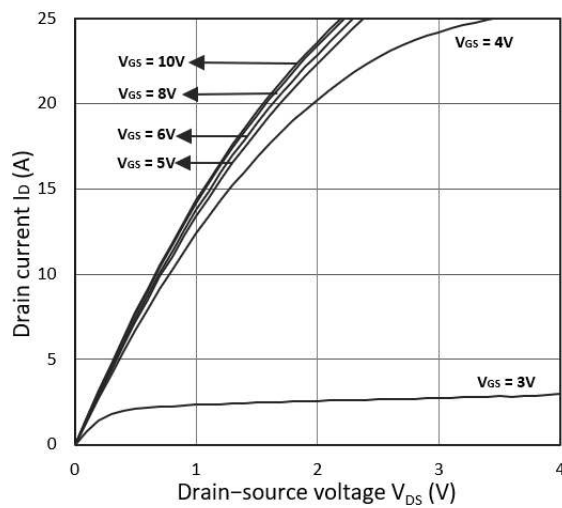


Figure 1. Output Characteristics

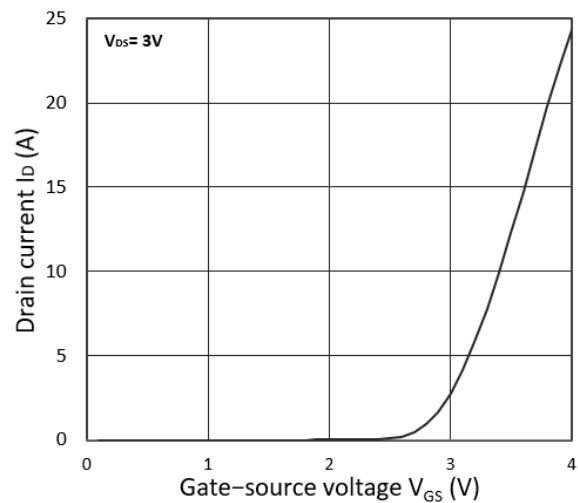


Figure 2. Transfer Characteristics

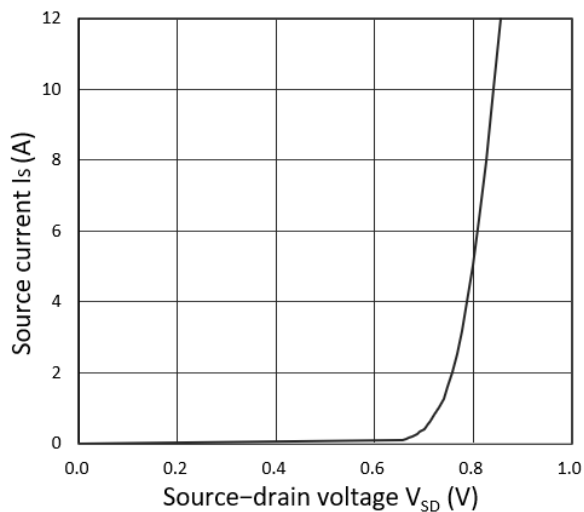


Figure 3. Forward Characteristics of Reverse

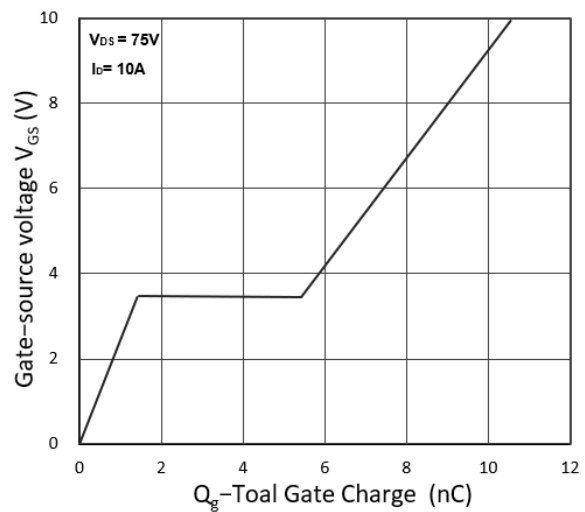
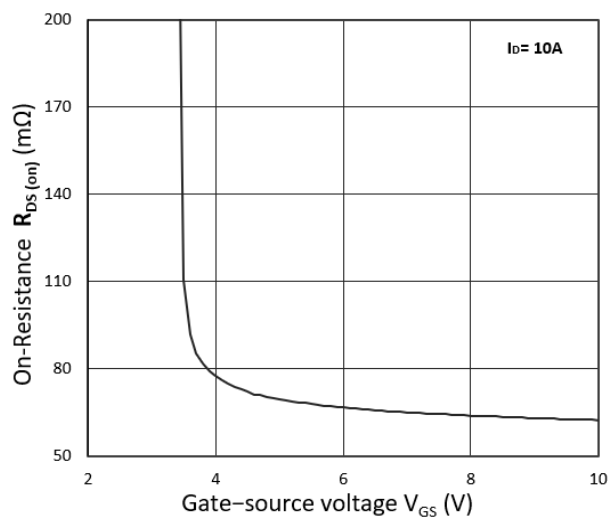
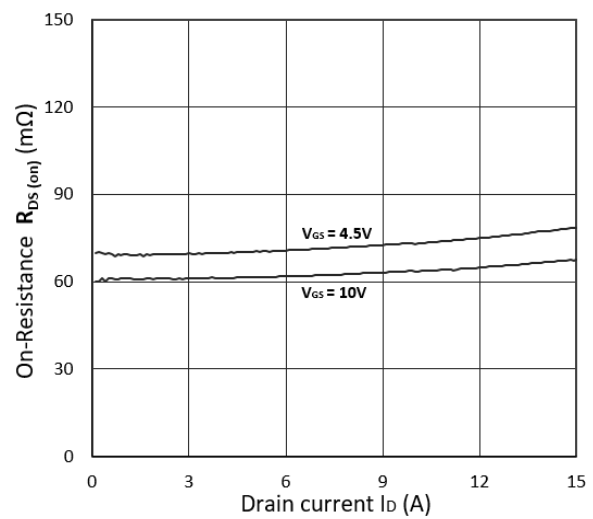


Figure 4. Gate Charge Characteristics

Figure 5.  $R_{DS(ON)}$  vs.  $V_{GS}$ Figure 6.  $R_{DS(ON)}$  vs.  $I_D$

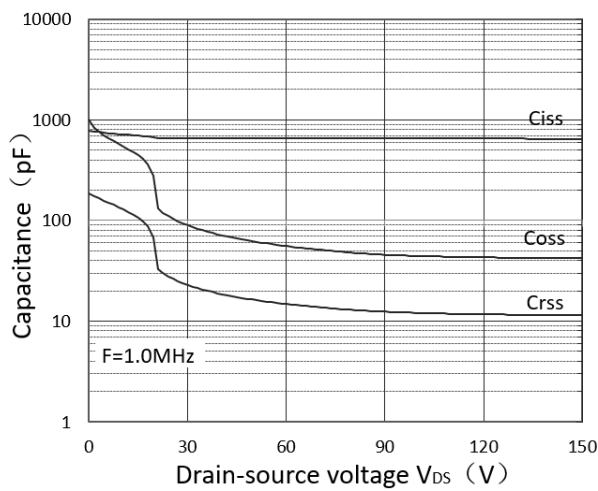


Figure 7. Capacitance Characteristics

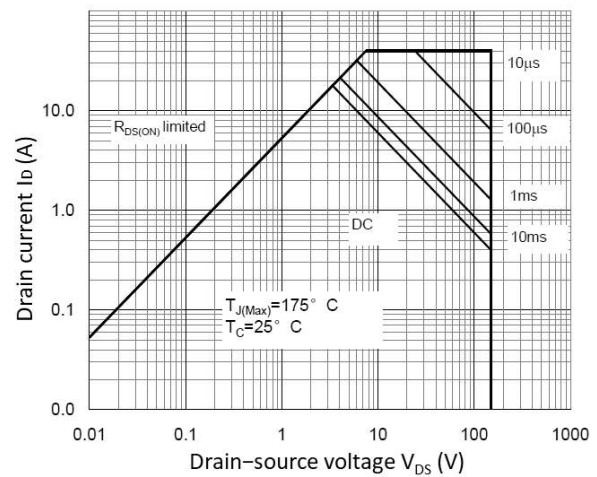


Figure 8. Safe Operating Area

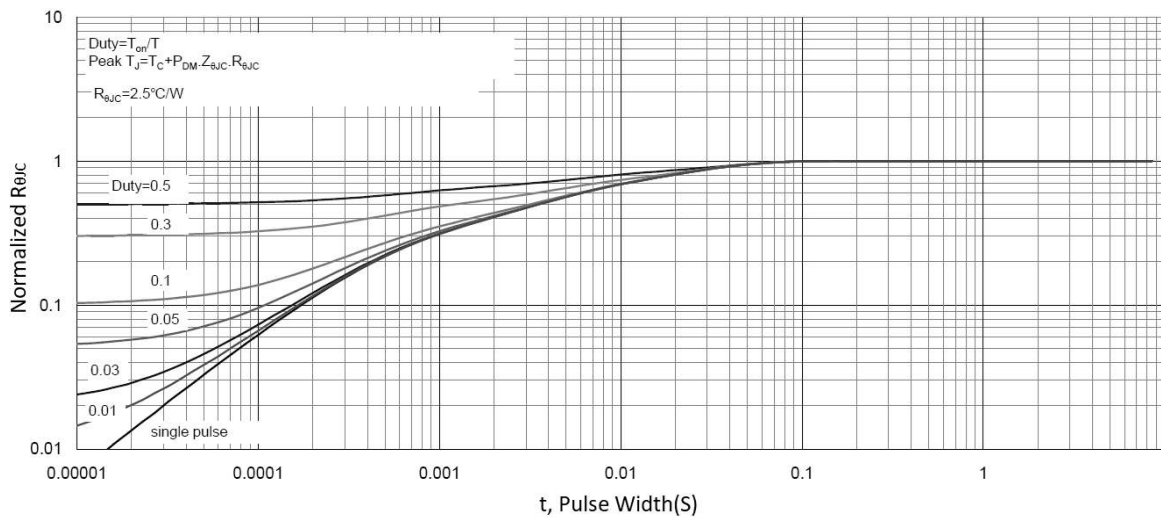


Figure 9. Normalized Maximum Transient Thermal Impedance

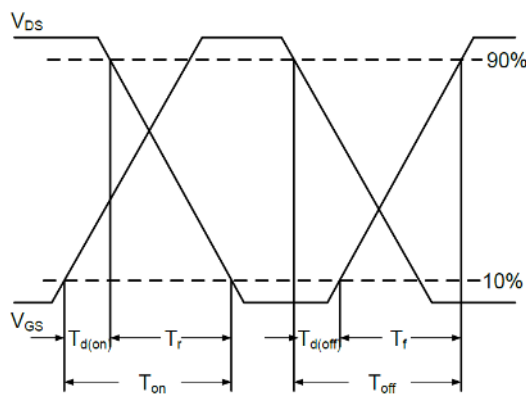
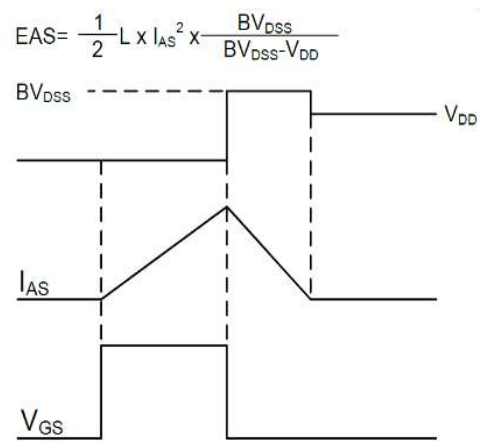
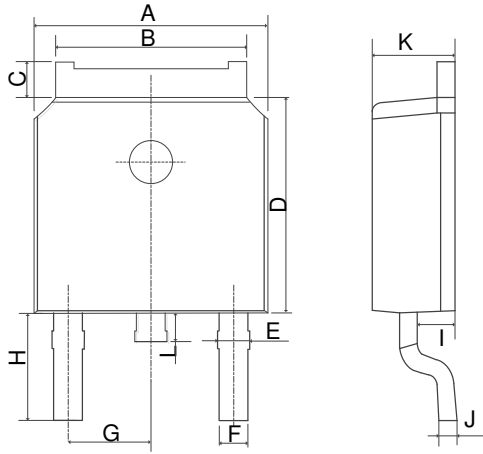


Figure 10. Switching Time Waveform

Figure 11. Unclamped Inductive Switching  
Waveform

## Mechanical Dimensions for TO-252

## COMMON DIMENSIONS

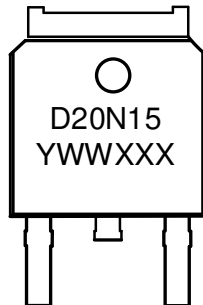


SYMBOL	MM	
	MIN	MAX
A	6.40	6.80
B	5.13	5.50
C	0.88	1.28
D	5.90	6.22
E	0.68	1.10
F	0.68	0.91
G	2.29REF	
H	2.90REF	
I	0.85	1.17
J	0.51REF	
K	2.10	2.50
L	0.40	1.00

## Ordering Information

Part	Package	Marking	Packing method
WMO20N15T1	TO-252	D20N15	Tape and Reel

## Marking Information



D20N15 = Device code

YWWXXX= Date code

## Contact Information

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